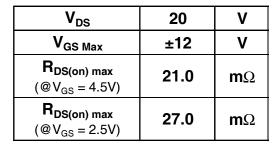
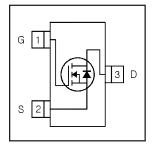


## HEXFET® Power MOSFET







### Application(s)

Load/ System Switch

#### **Features and Benefits**

#### **Features**

Low $R_{DS(on)}$ ( < 21m $\Omega$ )
Industry-standard SOT-23 Package
RoHS compliant containing no lead, no bromide and no halogen

#### **Benefits**

_	
	Lower conduction losses
results in	Multi-vendor compatibility
$\Rightarrow$	Environmentally friendly

**Absolute Maximum Ratings** 

Symbol	Parameter	Max.	Units
V <sub>DS</sub>	<b>Drain-Source Voltage</b>	20	V
I <sub>D</sub> @ T <sub>A</sub> = 25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	6.3	
I <sub>D</sub> @ T <sub>A</sub> = 70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	5.1	Α
I <sub>DM</sub>	Pulsed Drain Current	32	
P <sub>D</sub> @T <sub>A</sub> = 25°C	Maximum Power Dissipation	1.3	W
P <sub>D</sub> @T <sub>A</sub> = 70°C	Maximum Power Dissipation	0.80	VV
Linear Derating Factor		0.01	W/°C
$V_{GS}$	Gate-to-Source Voltage	± 12	V
$T_{J,}T_{STG}$	Junction and Storage Temperature Range	-55 to + 150	°C

### **Thermal Resistance**

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient ③		100	°C/W
$R_{\theta JA}$	Junction-to-Ambient (t<10s) ⊕		99	C/VV

#### ORDERING INFORMATION:

See detailed ordering and shipping information on the last page of this data sheet.

Notes ① through ④ are on page 10 www.irf.com

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## Electric Characteristics @ $T_J = 25$ °C (unless otherwise specified)

Symbol	Parameter	Min.	Тур.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	20			٧	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}\!/\!\Delta T_J$	Breakdown Voltage Temp. Coefficient		7.8	_	mV/°C	Reference to 25°C, I <sub>D</sub> = 1mA
D	Static Drain-to-Source On-Resistance		16.0	21.0	<b>~</b> 0	$V_{GS} = 4.5V, I_D = 6.3A$ ②
R <sub>DS(on)</sub>	Static Drain-to-Source Off-Resistance		22.0	27.0	mΩ	$V_{GS} = 2.5V, I_D = 5.1A$ ②
V <sub>GS(th)</sub>	Gate Threshold Voltage	0.5	0.9	1.1	V	$V_{DS} = V_{GS}, I_D = 10\mu A$
I <sub>DSS</sub>	Drain-to-Source Leakage Current			1.0		$V_{DS} = 16V, V_{GS} = 0V$
	Dialii-to-Source Leakage Current			150	μA	$V_{DS} = 16V, V_{GS} = 0V, T_{J} = 125^{\circ}C$
I <sub>GSS</sub>	Gate-to-Source Forward Leakage			100	nA	V <sub>GS</sub> = 12V
	Gate-to-Source Reverse Leakage			-100	IIA	V <sub>GS</sub> = -12V
R <sub>G</sub>	Internal Gate Resistance		1.7		Ω	
gfs	Forward Transconductance	17			S	$V_{DS} = 10V, I_D = 6.3A$
$Q_g$	Total Gate Charge		8.9			$I_D = 6.3A$
$Q_{gs}$	Gate-to-Source Charge		0.68		nC	V <sub>DS</sub> =10V
$Q_{gd}$	Gate-to-Drain ("Miller") Charge		4.4			V <sub>GS</sub> = 4.5V ②
t <sub>d(on)</sub>	Turn-On Delay Time		4.9			V <sub>DD</sub> =10V <sup>②</sup>
t <sub>r</sub>	Rise Time		7.5			I <sub>D</sub> = 1.0A
t <sub>d(off)</sub>	Turn-Off Delay Time		19		ns	$R_G = 6.8\Omega$
t <sub>f</sub>	Fall Time		12			V <sub>GS</sub> = 4.5V
C <sub>iss</sub>	Input Capacitance		700			V <sub>GS</sub> = 0V
C <sub>oss</sub>	Output Capacitance		140		pF	V <sub>DS</sub> = 16V
C <sub>rss</sub>	Reverse Transfer Capacitance		98			f = 1.0MHz

## **Source - Drain Ratings and Characteristics**

Symbol	Parameter	Min.	Тур.	Max.	Units	Conditions
Is	Continuous Source Current			1.3		MOSFET symbol
	(Body Diode)			1.0	Α	showing the
I <sub>SM</sub>	Pulsed Source Current		<u> </u>		_ ^	integral reverse
	(Body Diode) ①				32	p-n junction diode.
V <sub>SD</sub>	Diode Forward Voltage			1.2	V	$T_J = 25^{\circ}C$ , $I_S = 6.3A$ , $V_{GS} = 0V$ ②
t <sub>rr</sub>	Reverse Recovery Time		12	18	ns	$T_J = 25^{\circ}C$ , $V_R = 15V$ , $I_F = 1.3A$
Q <sub>rr</sub>	Reverse Recovery Charge		5.1	7.7	nC	di/dt = 100A/μs ②

# International TOR Rectifier

# IRLML6244TRPbF

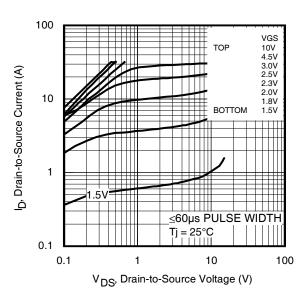


Fig 1. Typical Output Characteristics

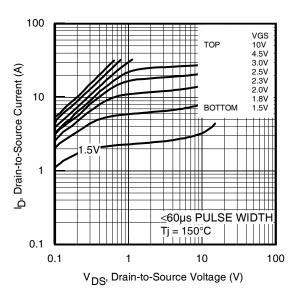


Fig 2. Typical Output Characteristics

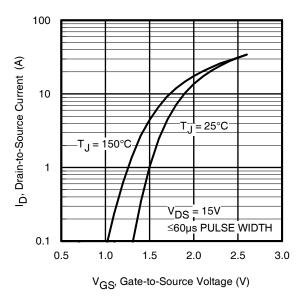
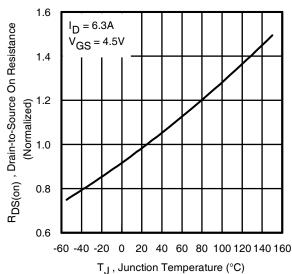
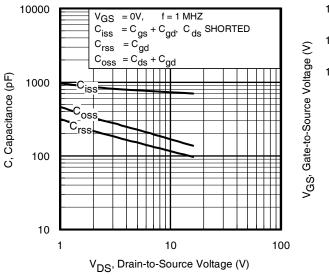


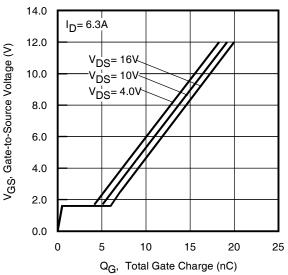
Fig 3. Typical Transfer Characteristics



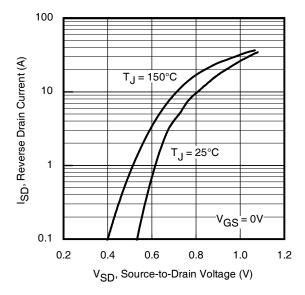
**Fig 4.** Normalized On-Resistance vs. Temperature



**Fig 5.** Typical Capacitance vs. Drain-to-Source Voltage



**Fig 6.** Typical Gate Charge vs. Gate-to-Source Voltage



**Fig 7.** Typical Source-Drain Diode Forward Voltage

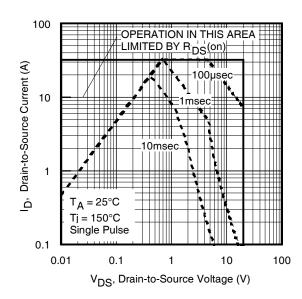
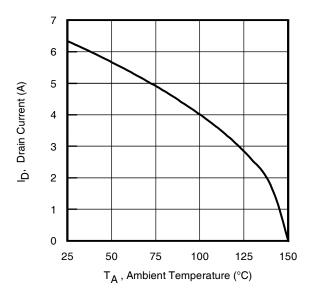


Fig 8. Maximum Safe Operating Area

# International TOR Rectifier

## IRLML6244TRPbF



**Fig 9.** Maximum Drain Current vs. Ambient Temperature

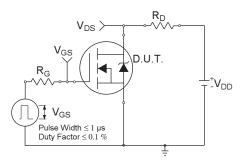


Fig 10a. Switching Time Test Circuit

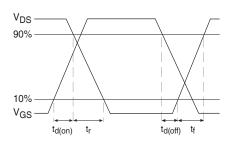


Fig 10b. Switching Time Waveforms

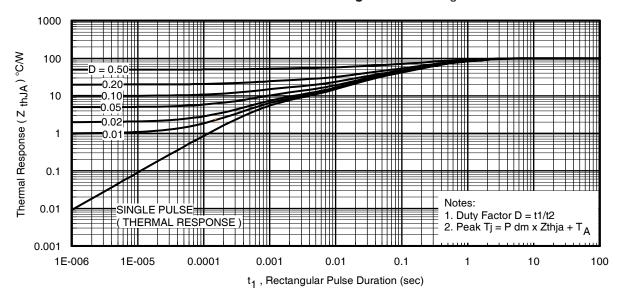
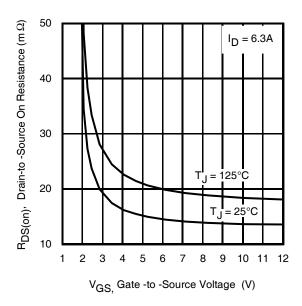
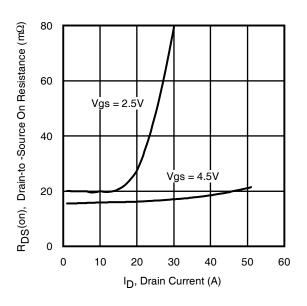


Fig 11. Typical Effective Transient Thermal Impedance, Junction-to-Ambient



**Fig 12.** Typical On-Resistance vs. Gate Voltage



**Fig 13.** Typical On-Resistance vs. Drain Current

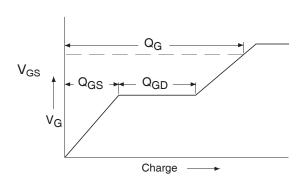


Fig 14a. Basic Gate Charge Waveform

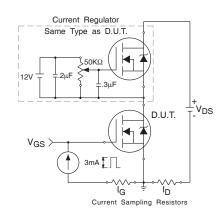
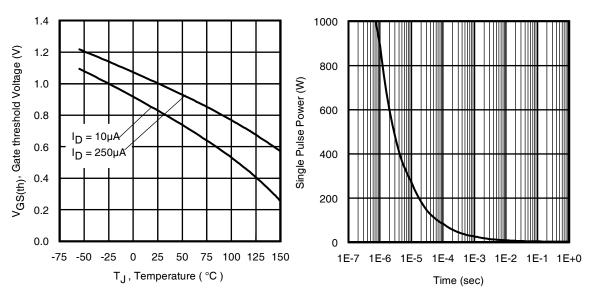


Fig 14b. Gate Charge Test Circuit

# International IOR Rectifier

# IRLML6244TRPbF



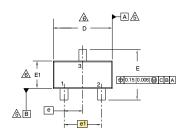
**Fig 15.** Typical Threshold Voltage vs. Junction Temperature

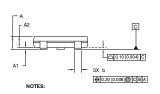
Fig 16. Typical Power vs. Time

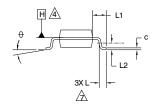
International IOR Rectifier

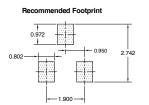
### Micro3 (SOT-23) Package Outline

Dimensions are shown in millimeters (inches)









DIMENSIONS					
SYMBOL	MILLIM	ETERS	INCHES		
STIVIBUL	MIN	MAX	MIN	MAX	
Α	0.89	1.12	0.035	0.044	
A1	0.01	0.10	0.0004	0.004	
A2	0.88	1.02	0.035	0.040	
b	0.30	0.50	0.012	0.020	
С	0.08	0.20	0.003	0.008	
D	2.80	3.04	0.110	0.120	
Е	2.10	2.64	0.083	0.104	
E1	1.20	1.40	0.047	0.055	
е	0.95	BSC	0.037	BSC	
e1	1.90	BSC	0.075	BSC	
L	0.40	0.60	0.016	0.024	
L1	0.54	REF	0.021	REF	
L2	0.25	BSC	0.010	BSC	
0	0	8	0	8	

DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1994
 DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].

3. CONTROLLING DIMENSION: MILLIMETER.

A DATUM PLANE H IS LOCATED AT THE MOLD PARTING LINE.

∠∆DATUM PLANE HIS LOCATED AT THE MICL D PARTINIS LINE.

ADATUM A AND B TO BE DETERMINED AT DATUM PLANE H.

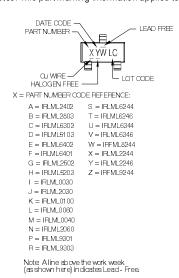
ADMINISIONS D AND BI ARE MEASURED AT DATUM PLANE H. DIMENSIONS DOES
NOT INCLUDE MOLD PROTRUSIONS OR INTERLEAD PLASH MICLD PROTRUSIONS
OR INTERLEAD PLASH SHALL NOT EXCEED 0.25 MI/(10.010 INCH) PER SIDE.

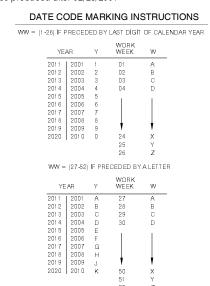
ADMENSION, IS THE LEAD LEASH SHALL SOFT EXCEED 1.25 MI/(10.010 INCH) PER SIDE.

B OUTLINE CONFORMS TO JEDEC OUTLINE TO 226 AB.

### Micro3 (SOT-23/TO-236AB) Part Marking Information

Notes: This part marking information applies to devices produced after 02/26/2001

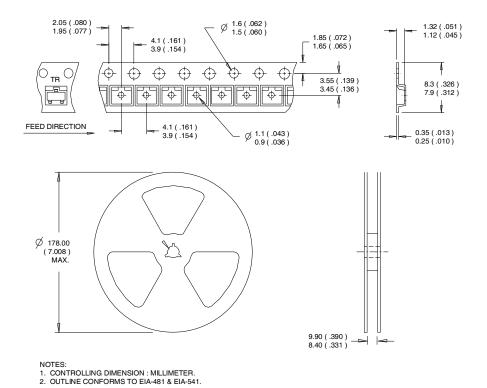




Note: For the most current drawing please refer to IR website at: http://www.irf.com/package/

## Micro3™ (SOT-23) Tape & Reel Information

Dimensions are shown in millimeters (inches)



Note: For the most current drawing please refer to IR website at: http://www.irf.com/package/

International

TOR Rectifier

Orderable part number	Package Type	Standard Pack		Note
-		Form	Quantity	
IRLML6244TRPbF	Micro3 (SOT-23)	Tape and Reel	3000	

#### Qualification information<sup>†</sup>

Qualification level	Consumer <sup>††</sup>			
	(per JEDEC JESD47F <sup>†††</sup> guidelines)			
Majatura Carajtiritud aval	Micro (COT 00)	MSL1		
Moisture Sensitivity Level	Micro3 (SOT-23)	(per IPC/JEDEC J-STD-020D <sup>†††</sup> )		
RoHS compliant	Yes			

- † Qualification standards can be found at International Rectifier's web site http://www.irf.com/product-info/reliability
- †† Higher qualification ratings may be available should the user have such requirements. Please contact your International Rectifier sales representative for further information: http://www.irf.com/whoto-call/salesrep/
- ††† Applicable version of JEDEC standard at the time of product release.

#### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Pulse width  $\leq$  400 $\mu$ s; duty cycle  $\leq$  2%.
- 3 Surface mounted on 1 in square Cu board.
- Refer to <u>application note #AN-994.</u>

Data and specifications subject to change without notice.



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